



Emerging metrology requirements for heterogeneous integration and 3D packaging – July 19, 2022



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[Emerging metrology requirements for heterogeneous integration and 3D packaging](#)

The ability to speed up the deployment of heterogeneous integration in mass production requires new and more frequent types of measurements in key manufacturing processes, including wafer and die bonding as well as lithography. [More>>](#)

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Growth is expected as revenues are predicted to increase by 7.5% in 2022 to reach almost US\$2.3 billion. [More>>](#)



Tech News

[Rambus expands portfolio of DDR5 memory interface chips for data centers and PCs](#)

Rambus Inc. announced the expansion of its DDR5 memory interface chip portfolio with the addition of the Rambus SPD (Serial Presence Detect) Hub and Temperature Sensor. [More>>](#)

FEATURED PRODUCT

[Fast Leak Detection](#)

The Pfeiffer Vacuum ASM 390 / ASM 392 dry, mobile leak detectors are optimized for rapid pump downs and short response times. They offer high sensitivity for ultra-clean maintenance of large test chambers. Semi S2 compliant, the ASM 390 / ASM 392 offer rugged and reliable use and an ergonomic platform. [Learn more.](#)

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Featured Video

EMD Electronics' Digital Solutions organization focuses on leveraging data in R&D, quality, and supply chain to solve industry challenges and accelerate learning cycles. Customers can proactively identify the parameters that matter for their fab performance before excursions occur. They can also gain better control of newly identified parameters to improve the performance of materials in their fabs, which can contribute to yield optimization. The learnings are also useful in R&D for new material innovation which accelerates the ramp up of next generation technology nodes. Watch this video interview with **Kutup Kurt, Head of Operations, Digital Solutions at EMD Electronics** to learn more.

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Kutup Kurt
Head of Operations, Digital Solutions
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EMD Electronics — Digital Solutions to Accelerate Semiconductor Innovation



44th EOS/ESD Symposium, September 18 – 23, 2022 at the Peppermill in Reno, NV

Our program is packed featuring a modular three-track design that gives you complete flexibility to pick and choose what interests you. We cannot wait to see you in person and get back to what makes conferences great – YOU and ME - and US – interacting, sharing, networking, learning, asking questions. [Learn more.](#)

Business News

Palomar Technologies expands Innovation Center-Singapore

Palomar Technologies announced today the expansion of its Innovation Center in Singapore to meet a growing demand in Southeast Asia for process development and specialty OSAT for advance semiconductor new product introductions. [More>>](#)

Moov secures David Arkow as head of global sales to further leadership in used semiconductor equipment market

Moov, a data-fueled marketplace for used semiconductor manufacturing equipment, today welcomed David Arkow as the company's head of global sales. [More>>](#)

Webinars and Technology Papers

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